



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**PATENT**

In re application of: PATRICK et al.

Attorney Docket No.:  
LAM1P061/P0318

Application No.: 08/925,985

Examiner: MARKOFF, A.

Filed: September 9, 1997

Group: 1746

Title: APPARATUS FOR IMPROVING ETCH  
UNIFORMITY AND METHODS  
THEREFOR

9/1  
00  
5-31-00

**CERTIFICATE OF EXPRESS MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service on May 12, 2000, in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label EL132614630US, addressed to: Box CPA, Assistant Commissioner for Patents, Washington, D.C. 20231.

Signed:

*Sue Funchess*  
Sue Funchess

**PRELIMINARY AMENDMENT B**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Enclosed is a preliminary amendment in response to the Office Action dated March 1, 2000.

**In the Claims:**

Please cancel claim 3 and the original claims 11-24 and claims 34-35. Please amend claims 1 and 25-35, as follows:

1. (Twice Amended) In a plasma processing chamber, a method for improving etch uniformity while etching a semiconductor substrate, comprising:

placing said semiconductor substrate into a sacrificial substrate holder, said sacrificial substrate holder being configured to present a sacrificial etch portion surrounding said semiconductor substrate to a plasma within said plasma processing chamber to permit said plasma to etch a first surface of said semiconductor substrate and a first surface of said